

| 更改<br>REV | 修改内容<br>MODIFICATION |
|-----------|----------------------|
| A         | EC04203              |
| B         | EC04206              |
| C         | EC04217              |

Note:

1.Material:

Housing: LCP

Contact: C5210-SH, T: 0.20 mm

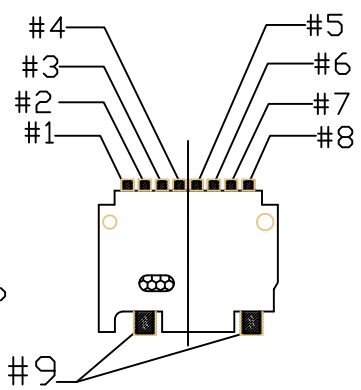
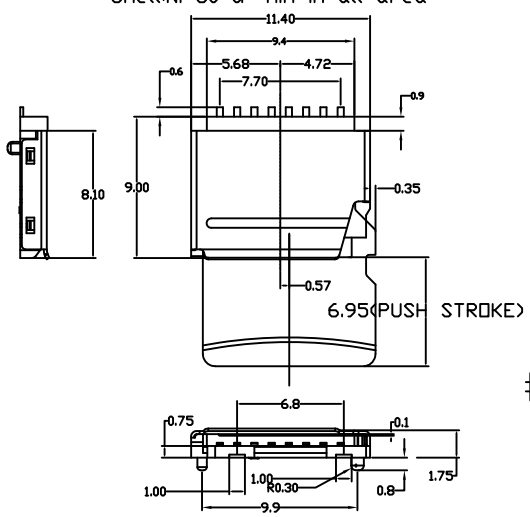
Shell: SPCC, T: 0.20 mm

2.Plating:

Contact: G.F on contact area and Ni over all area for underplated

Mate tin 50 u" min in solder tail

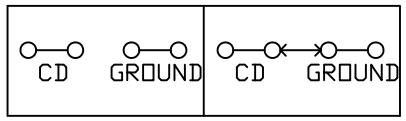
Shell: Ni 50 u" min in all area



| PIN NO | DESCRIPTION |
|--------|-------------|
| #1     | D2          |
| #2     | D3          |
| #3     | CD          |
| #4     | CMD         |
| #5     | PW          |
| #6     | CLK         |
| #7     | D0          |
| #8     | D1          |
| #9     | GND         |

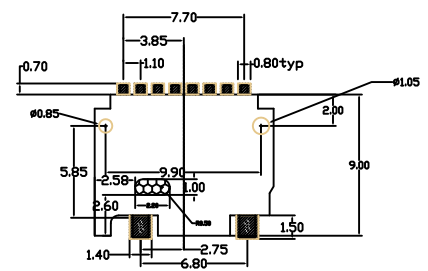
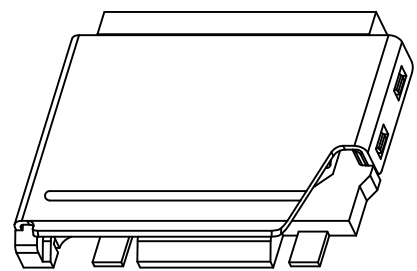
RECOMMENDED PC BOARD LAYOUT  
TOLERANCE: ±0.05mm

CIRCUIT:



WITHOUT  
CARD

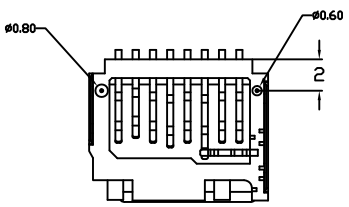
MICRO SD  
CARD  
INSERTED



RECOMMENDED PC BOARD LAYOUT  
(component side) TOLERANCE: ±0.05mm

7MSDP-FA-X019

0:TRAY  
1:RELL



| GENERAL TOLERANCE |               | KINGCONN 皇海科技股份有限公司              |                |
|-------------------|---------------|----------------------------------|----------------|
| X± 0.50           | X*± 5 °       | 名 称/TITLE<br>MICRO SD CONN-1.75H |                |
| X± 0.30           | X*± 2 °       |                                  |                |
| .XX± 0.20         | .XX*± 1 °     |                                  |                |
| 单 位(UNIT)         | 料 号(PART NO.) | 图 号(DWG NO.)                     | 张 数(SHEET)     |
| mm                | 7MSDP-FA-X019 | 7MSDP-FA-X019-c                  | 1/1            |
| 审 核(CHECKED)      | 制 图(DRAWN)    | SCALE 1:1                        | 图 号(SHEET) 1/1 |
| PROJ.             | REV C         | SCALE 1:1                        | 图 号(SHEET) 1/1 |

